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ROBERT SMITH
Software Engineering Intern II

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Phone: (0123)-456-789

SUMMARY

Programming and Scripting Languages: C, C#, Python, MATLAB, Assembly Language, Web Development Languages: PHP, HTML5, CSS3, Database: MySQL, Oracle, Computer Skills: MS Office, Simulink, HFSS, COMSOL, CoventorWare, Circuit Maker, Pspice, Keil uVision5, Hardware Skills: Arduino, Microprocessor (Microcontroller 8051, Freescale, Semiconductor Processing: Device fabrication (Micro/Nano), Photolithography, Etching, Patterning Photoresist, Thin film deposition, Microfluidic mixing.

SKILLS

Programming And Scripting Languages: C, C#, Python.

WORK EXPERIENCE

Software Engineering Intern II

ABC Corporation - September 2015 – December 2016

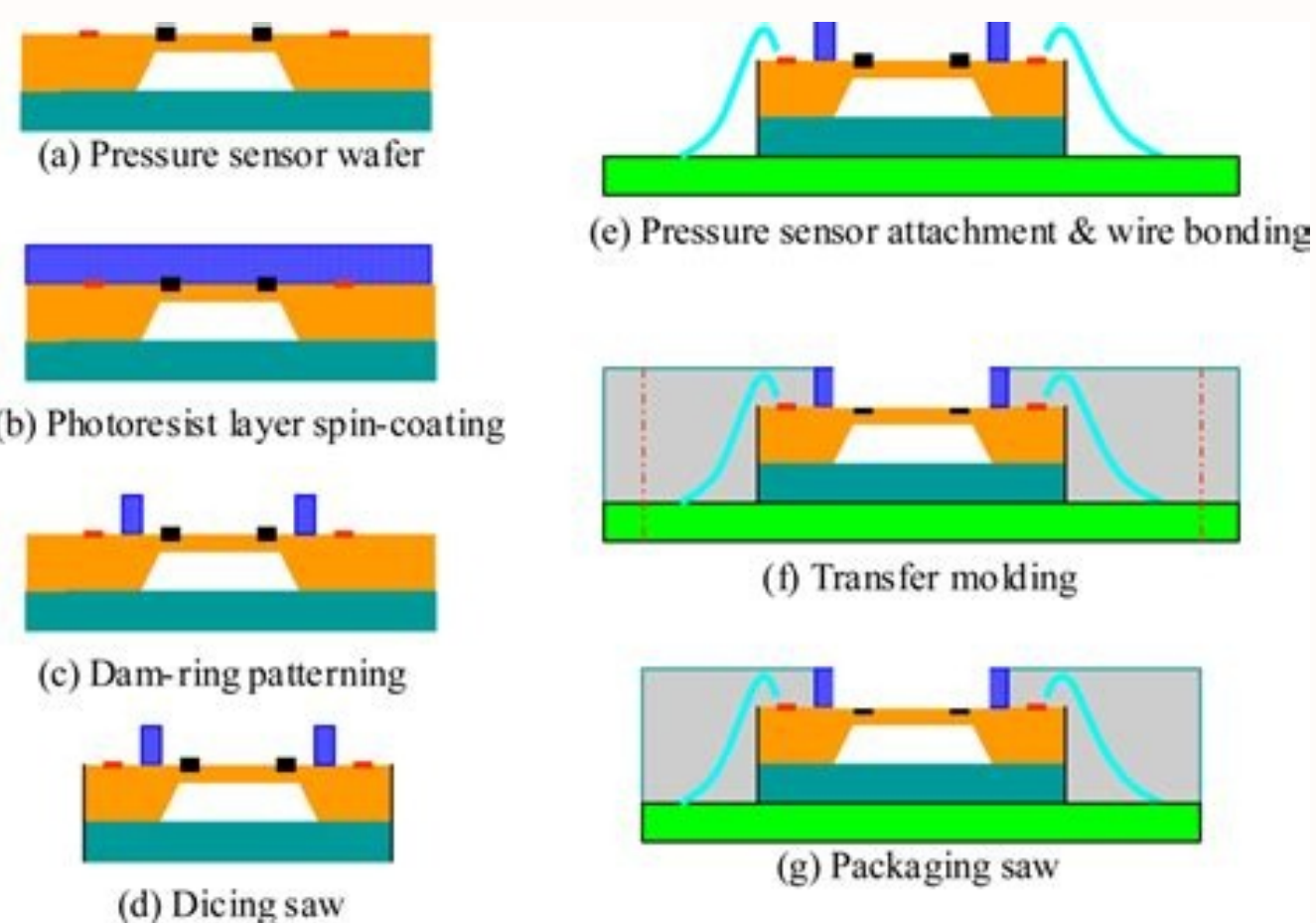
- Installed test benches in Automation domain & making the setup for Maserati and Subaru Infotainment Systems.
- Operated Harman Test Automation Framework to generate logs and reports for failed test cases.
- Documented Test Automation Framework installation, setup procedure for the Infotainment Systems.
- Generated an .exe file using C# scripting to open URLs containing necessary files with button click options for installation of Harman Test Automation Framework.
- Assisted in modifying test cases for Automation domain using C#.
- Generated ATS (Accessory Test System) traces, logs, tickets for failed test cases.
- Documented necessary commands & lingos by invoking actions for iAP1 & iAP2 test cases using ATS.

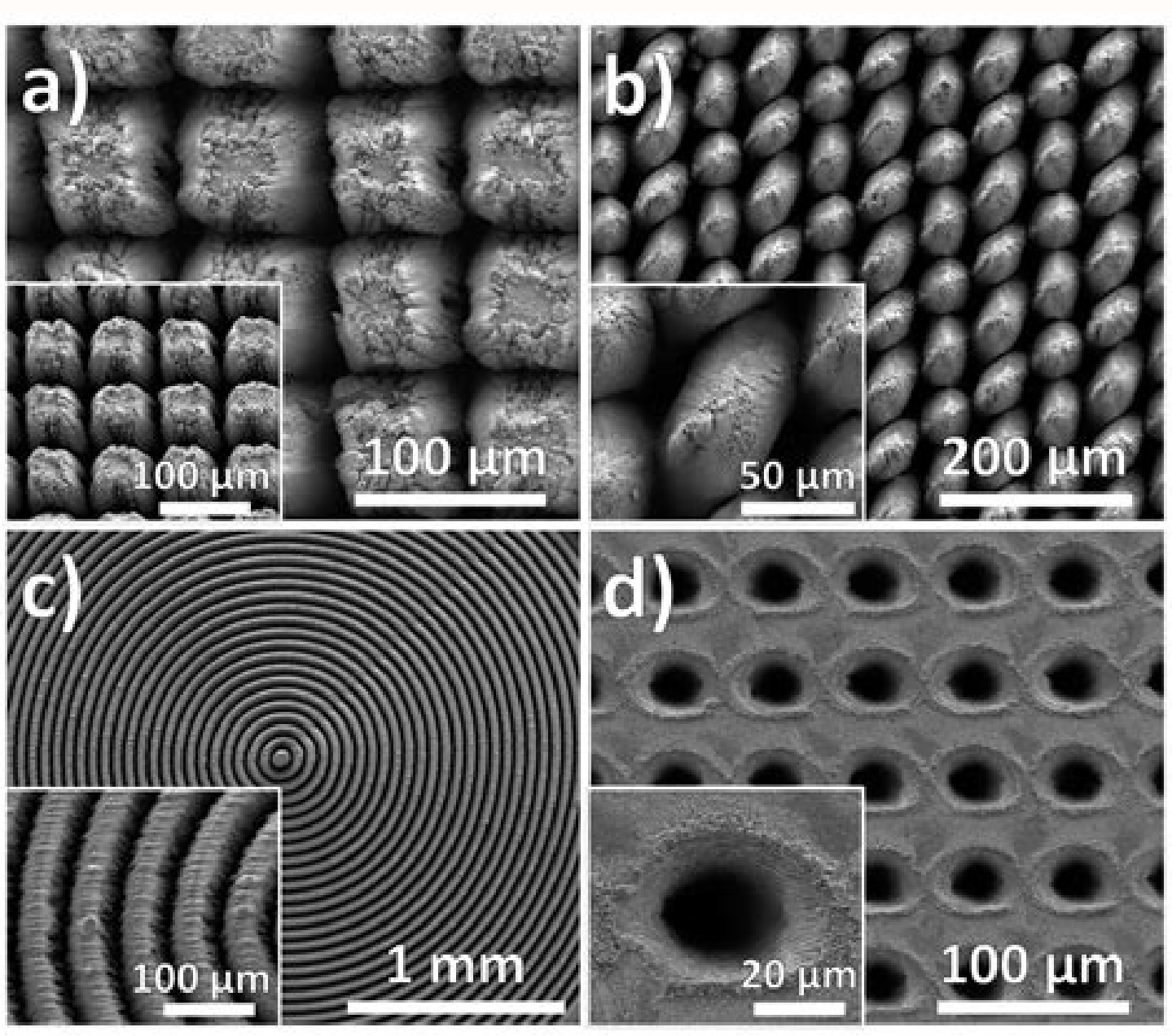
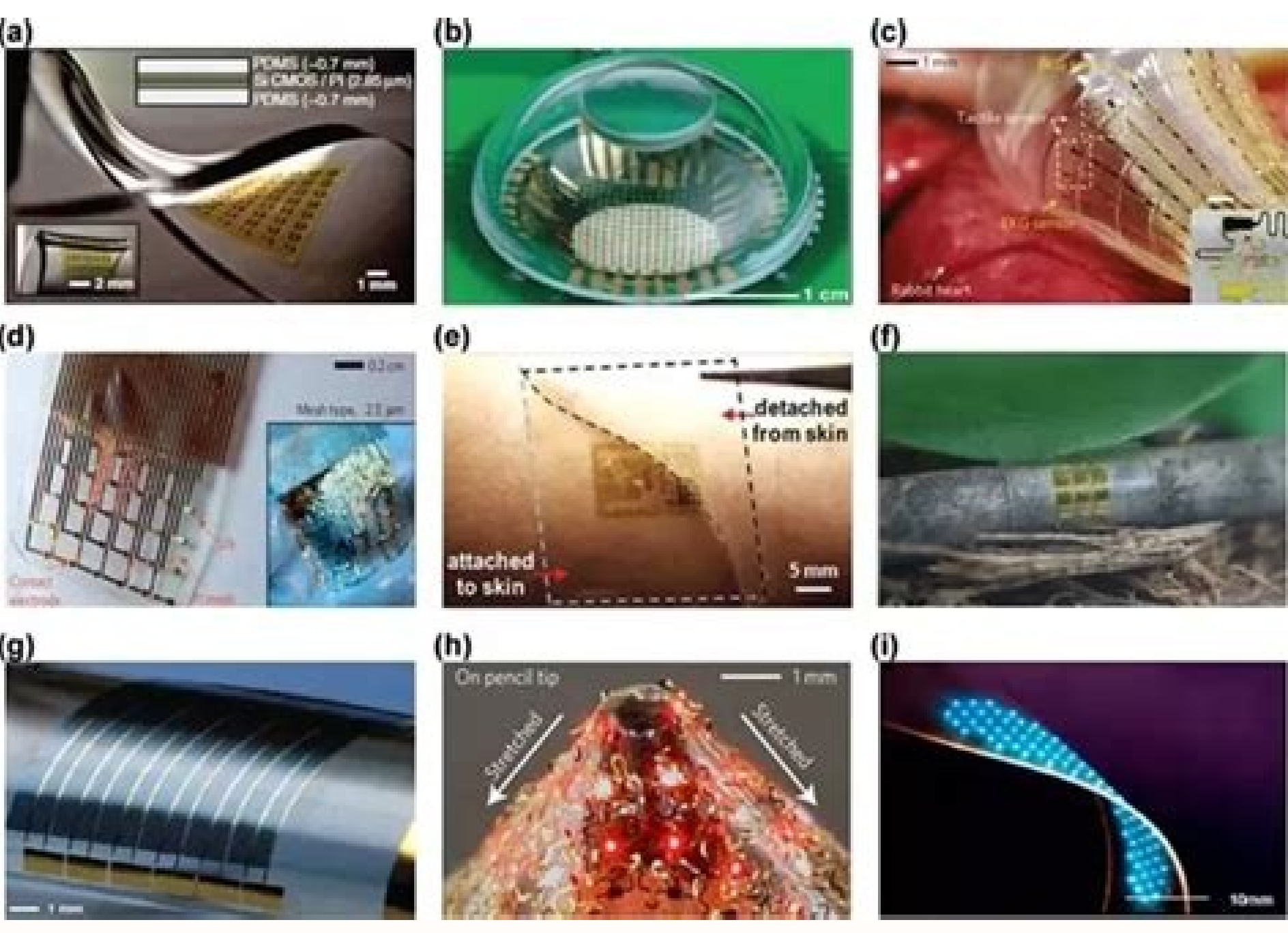
Software Engineering Intern

Delta Corporation - 2014 – 2015

- Worked with innovation team and contributed to technical architecture, design and code of mobile applications in the area of automotive and vehicular .
- Illinois SPX Genfare Corporation is a leader in providing customized fare solutions to transit agencies of all sizes throughout North America.
- As a software engineering intern at SPX Genfare, I was involved in the development of new SaaS product for the company Genfare Cloud which is hosted .
- Being a part of cloud development team, my main role was in implementation of database management and various other modules to add the multi-tenancy .
- Also assisted QA team to test and verify functionalities of the system.
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Properties of selected semiconductor materials Appendix III. Conversion Factors Appendix V. Physical Deposition: Evaporation and Sputtering Phase Diagrams 12.1. Sublimation and Evaporation * 12.2 Deposition Rates 12.3 Steps 12.4 Evaporation Systems: Crucible Heating Techniques 12.5 Films more components 12.6 Introduction to Sputtering 12.7 Sputtering physics * 12.8 Deposition rate: 12.10 Morphology and coverage of step 12.11 Sputtering methods 12.12 Sputtering of specific materials 12.13 Stress in the layers deposited 12.14 Summary of problems References Chapter 13. 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F Values Index of void and plasmas 10.1 The kinetic gas theory * 10.2 Gas flow and conductance 10.3 Pressure intervals and empty blank noitceorP 8.9 yhpargohtil VUE 7.9 yar-X ytimixorP rof sksaM enarbmeM 6.9 smetsyS erusopxE yar-X ytimixorP 5.9 *secruoS VUE dna yar-X 4.9 kooltuO dna yrammuS yhpargohtil, maeB nortceIE etirW-tceirID 3.9 smetsyS yhpargohtil, maeB nortceIE etirW-tceirID 2.9 *rettaM hitw smaeB ygreB hgiH fo snoitcairetNI 1.9 **sequincheT cilpargohtil, lacticponON .6 retpahC secnerefeR smelborP yrammuS 01.5 **seliforP detnalplmI laciremunN 9.5 sruceNoC dna smelborP :smetsyS noitlatnalplmI nol 8.5 **scitceleID detrub 7.5 **noitramroF noitcunJ wollaS 6.5 eqamaD noitlatnalplmI 5.5 eqnaR detceorP laretaL dna gnilemahC 4.5 eqnaR detceorP lacitreV 3.5 *gniretaeS bmluoC 2.5 smetsyS noitlatnalplmI nol dezilaedi 1.5 noitlatnalplmI nol. II xidneppa slobnyS nommoC dna smynorca. 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Basic operation of the MESFET 17.2 Basic MESFET technology 17.3 Digital technologies 17.4 MMIC technologies 17.5 Modfet 17.6 Revision of bipolar devices: ideal and almost ideal behavior 17.7 BJT performance 17.8 Bipolar initials 17.9 Advanced bipolar processes 17.10 Bow 17.11 Thin movie transistors 17.12 Summary of problems References Chapter 18. * = This section aznes aznes assemo eresse 'Aup e atznav a elairetam eneitnoc enoizes atseuQ = ** esab id elairetam scitceleID fo gnissecorP lamreht dipaR 6.6 seiturupmI fo noitavitca lamreht dipaR 5.6 **sertS citsalpomreht 4.6 tmemrusaeM erutarepmeT 3.6 ngiseD rebmahC dna secruoS lacticpO ytsinetNI hgiH 2.6noitprosa lacticpO dna ,egnahcxE taeH ,noitait daR ydoB yarG 1.6 gnissecorP lamreht dipaR .3 retpahCNOITATNALPMI NOI DNA GNISSECORP TOH :I SESSECORP TINU .V TRAP secnerefeR smelborP yrammuS 41.41 **yxatipE maeB lacimehC dna EBM ecruoS saG 31.41 **yroehT FCB 21.41 yxatipE maeB raluceloM 11.41 sequincheT htworG laixatipE esahP ropav nocilis deavnad 01.41)DVCOM(notitisopeD ropav lacimehC cinagro lateM 9.41 yxatipeoreteH royal deniarsT dna etarusnemmoenI 8.41 yxatipE esahP ropav G tropsnarT edilaH 7.41 *htworG evitceleS 6.41 htworG laixatipE ni stcefeD 5.41 noitaroprocnI tnapoD 4.41 snoitcaeR ecafrus 3.41 htworG esahP ropav fo scimanydomreht eht 2.41 lavomeR edixO evitaN dna gninaelC refaW 1.4 htworG laixatipE .2 retpahCyrammuS 4.1esrucO eht rof pamdaoR A 3.1seigolonheT dna sessacorP tinU 2.1elpmaxE elpmS A ,seigolonheT cinortceiorcIM 1.noitacirbaF cinortceiorcIM oI noitcudortni na ,I xidneppa secnerefeR smelborP yrammu 11.91scidulloraim 11.91 JSMRAHYgolonheT smetsysorcIM oltaR tcepsa hgiH 01.91ssecorP gnihcamorciM ecafrus 9.91 scisaB gnihcamorciM ecafrus 7.91wolf ssecorP gnihcamorciM kluB 6.91 sek ucqincheT gnihcE gnihcamorciM kluB 5.91 seivcD SMEM name C fo scinaheM 4.91 noitcudsnarT lacitrcleO-of-lacinaheM 3.91 smiIF nihT ni ssertS 2.91 scinaheM fo slatnemadnuhF 1.91 SMEM .9 retpahC secnerefeR smelborP yrammuS 9.8 **sc 8.3 stceffe erusopxE redroD dnocse 7.8 tsiserotahP gnioleveD dna qniylppa 6.8 noitcunF refsnarT noitaludoM lacitrc eht 5.8 sevruc tsartnoC 4.8 tsiserotahP evitsoP NQD fo snoitcaeR lacipyT 3.8 *sremyoP dna slairetaM cinagro 2.8 sepyT tsiserotahP 1.8 tsiserotahP .I TRAP.esruc eht fo tmetnoc cisab eht fo .III .III TRAP secnerefeR smelborP yrammuS 9.6 smetsyS gnissecorP lamreht dipaR evitanreIA 8.6 noitamroF tcatnoC dna noitadicils

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